

ABSTRACT OF THE DISCLOSURE**Molding Apparatus**

Molding apparatus (200) is provided for simultaneously molding a molding
5 material around a number of separate substrates, each substrate having a
semiconductor chip mounted thereon. The apparatus includes a mold holder
(113a, 113b, 114, 103) having a first holding section for holding a first mold half
(119) and a second holding section for holding a second mold half (120). The
first and second holding sections have a common support surface (135), the
10 support surface (135) including a first movable member (104a) in the first
holding section and a second movable member (104b) in the second holding
section. The first and second movable members (104a, 104b) are movable
between a first position in which they protrude out of the support surface (135)
and a second position in which the protrusion from the support surface (135) is
15 less than in the first position. A first drive mechanism (100, 110) is coupled to
the first movable member (104a) and a second drive mechanism (100, 110) is
coupled to the second movable member (104b). The first and second drive
mechanisms (100, 110) are adapted to be independently actuated to move the
first and second movable members (104a, 104b) between the first and second
20 positions.